

## 8.0A Super Fast Recovery Rectifier Bridge

**Reverse Voltage - 300 to 600 V  
Forward Current – 8.0A**

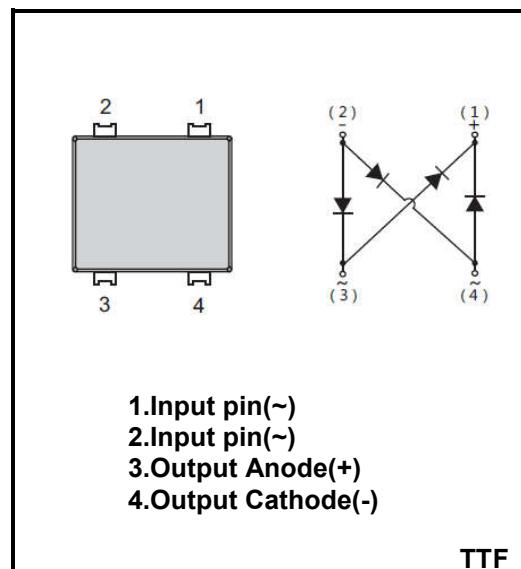
### FEATURES

- ◆ High current capability
- ◆ Low forward voltage drop
- ◆ Glass Passivated Chip Junction
- ◆ Designed for Surface Mount Application
- ◆ Lead free in comply with EU RoHS 2011/65/EU directives



### MECHANICAL DATA

- ◆ Case:TTF
- ◆ Terminals: Solderable per MIL-STD-750, Method 2026
- ◆ Approx. Weight: 0.461g / 0.0163oz



**TTF**

### Maximum Ratings and Electrical characteristics

Ratings at 25 °C ambient temperature unless otherwise specified.

Single phase half-wave 60 Hz, resistive or inductive load, for capacitive load current derate by 20 %

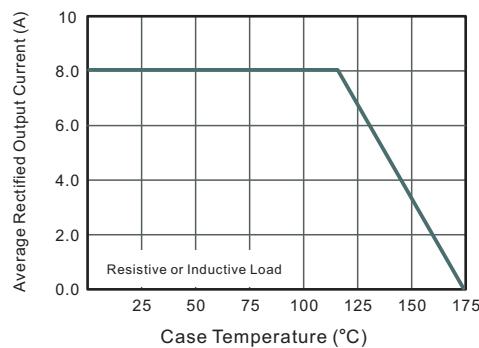
Parameter	Symbols	TTF803E	TTF806E	Units
Maximum Repetitive Peak Reverse Voltage	$V_{RRM}$	300	600	<b>V</b>
Maximum RMS voltage	$V_{RMS}$	200	420	<b>V</b>
Maximum DC Blocking Voltage	$V_{DC}$	300	600	<b>V</b>
Average Rectified Output Current	$I_{(AV)}$	8.0		
Peak Forward Surge Current 8.3 ms Single Half Sine-Wave Superimposed on Rated Load (JEDEC method)	$I_{FSM}$	220		
Peak Forward Surge Current 1.0 ms Single Half Sine-Wave Superimposed on Rated Load	$I_{FSM}$	350		
Forward Voltage per element @ $I_F = 8A$ DC	$V_F$	1.20	1.50	<b>V</b>
Maximum Reverse Recovery Time	$Tr_{rr}$	35		
Maximum DC Reverse Current @ $T_a=25^\circ C$ at Rated DC Blocking Voltage @ $T_a=125^\circ C$	$I_R$	5		
		500		
I <sup>2</sup> t Rating for Fusing(3ms≤t≤8.3ms)	$I^2t$	200		
Typical Junction Capacitance	$C_j$	100		
Typical Thermal Resistance	$R_{\theta JA}$ $R_{\theta JC}$ $R_{\theta JL}$	60 10 12		
Operating and Storage Temperature Range	$T_j$ , $T_{stg}$	-55 ~ +175		

(1) Measured at 1 MHz and applied reverse voltage of 4 V D.C

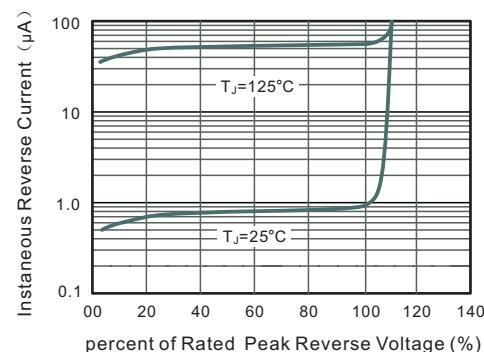
(2) Mounted on glass epoxy PC board with 4×1.5"×1.5" (3.81×3.81 cm) copper pad.

## Ratings and Characteristic Curves

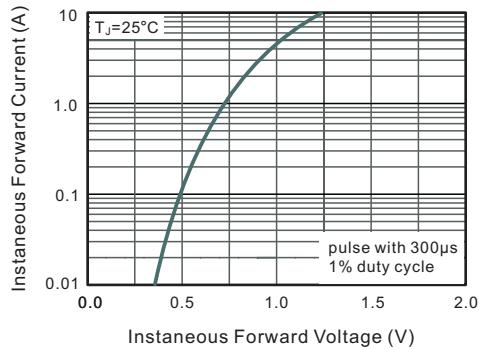
**Fig.1 Average Rectified Output Current Derating Curve**



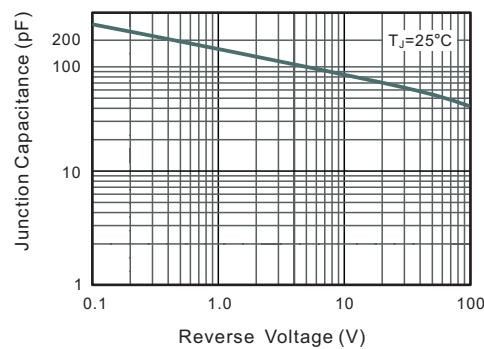
**Fig.2 Typical Reverse Characteristics**



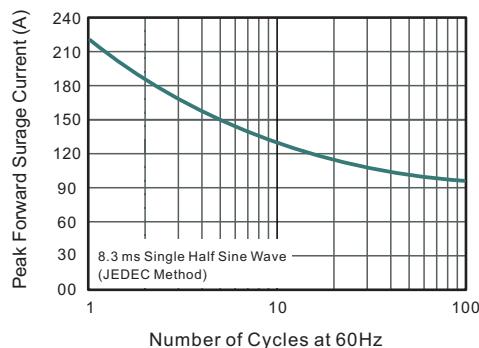
**Fig.3 Typical Instantaneous Forward Characteristics**



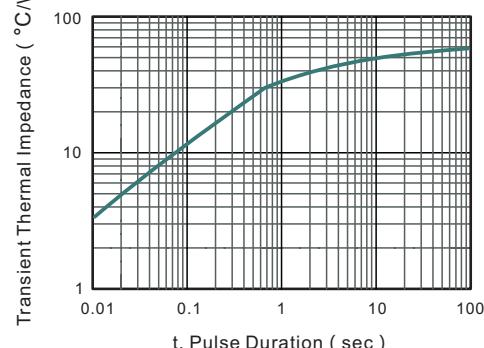
**Fig.4 Typical Junction Capacitance**

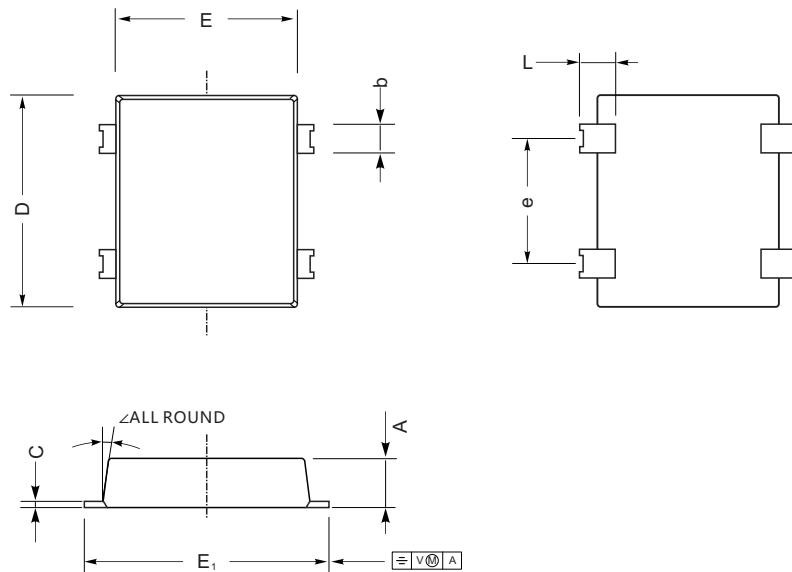


**Fig.5 Maximum Non-Repetitive Peak Forward Surge Current**

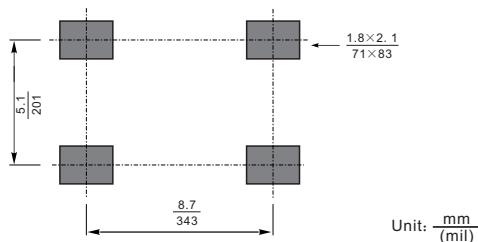


**Fig.6- Typical Transient Thermal Impedance**



**Package Outline**
**TTF**
**Plastic surface mounted package; 4leads**


UNIT		A	C	D	E	$E_1$	L	e	b	$\angle$
mm	max	1.75	0.55	9.8	8.8	10.2	1.25	5.3	1.55	$10^\circ$
	min	1.35	0.25	9.4	8.4	9.8	0.85	4.9	1.25	
mil	max	68	21.6	385	346	401	49	209	61	$10^\circ$
	min	53	9.8	370	330	385	33	193	49	

**The recommended mounting pad size**

**Summary of Packing Options**

Package	Packing Description	Packing Quantity	Industry Standard
TTF	Tape/Reel,13"reel	3000	EIA-481-1